

REJ03D0265–0200Z (Previous ADE-205-386 (Z)) Rev.2.00 Jul.16.2004

Description

The HD74AC273 has eight edge-triggered D-type flip-flops with individual D inputs and Q outputs. The common buffered Clock (CP) and Master Reset (\overline{MR}) inputs load and reset (clear) all flip-flops simultaneously.

The register is fully edge-triggered. The state of each D input, one setup time before the Low-to-High clock transition, is transferred to the corresponding flip-flops's Q output

All outputs will be forced Low independently of Clock or Data inputs by a Low voltage level on the \overline{MR} input. The device is useful for applications where the true output only is required and the Clock and Master Reset are common to all storage elements.

Features

- Ideal Buffer for MOS Microprocessor or Memory
- Eight Edge-Triggered D Flip-Flops
- Buffered Common Clock
- Buffered, Asynchronous Master Reset
- See HD74AC373 for Transparent Latch Version
- See HD74AC374 for 3-State Version
- Outputs Source/Sink 24 mA
- Ordering Information

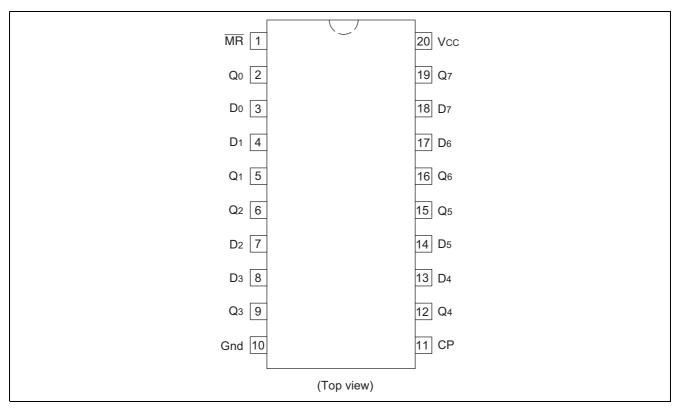
Part Name	Package Type	Package Code	Package Abbreviation	Taping Abbreviation (Quantity)
HD74AC273P	DIP-20 pin	DP-20N	Р	
HD74AC273FPEL	SOP-20 pin (JEITA)	FP-20DAV	FP	EL (2,000 pcs/reel)
HD74AC273RPEL	SOP-20 pin (JEDEC)	FP-20DBV	RP	EL (1,000 pcs/reel)

Notes: 1. Please consult the sales office for the above package availability.

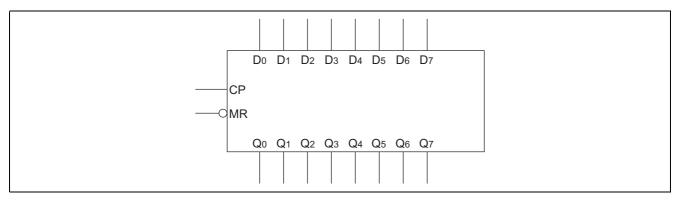


^{2.} The packages with lead-free pins are distinguished from the conventional products by adding V at the end of the package code.

Pin Arrangement



Logic Symbol

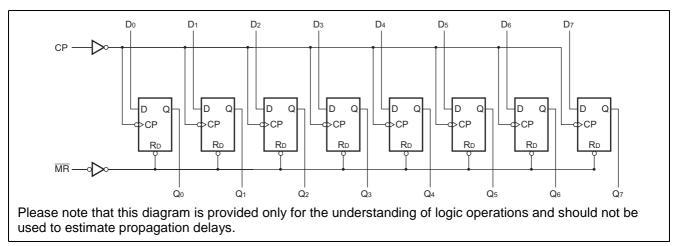


Pin Names

$D_0 - D_7$	Data Inputs
MR	Master Reset
СР	Clock Pulse Input
Q_0-Q_7	Data Outputs



Logic Diagram



Mode Select-Truth Table

		Inputs	Outputs	
Operating Mode	MR	СР	D _n	Q _n
Reset (Clear)	L	Х	Х	L
Load "1"	Н		Н	Н
Load "0"	Н		L	L

H : High Voltage Level

L : Low Voltage Level

X : Immaterial

: Low-to-High Clock Transition

Absolute Maximum Ratings

Item	Symbol	Ratings	Unit	Condition
Supply voltage	V _{cc}	–0.5 to 7	V	
DC input diode current	I _{IK}	-20	mA	$V_1 = -0.5V$
		20	mA	$V_1 = Vcc+0.5V$
DC input voltage	V	-0.5 to Vcc+0.5	V	
DC output diode current	Ι _{οκ}	-50	mA	$V_{\rm O} = -0.5V$
		50	mA	$V_{O} = Vcc+0.5V$
DC output voltage	Vo	-0.5 to Vcc+0.5	V	
DC output source or sink current	I _o	±50	mA	
DC V _{cc} or ground current per output pin	I _{CC} , I _{GND}	±50	mA	
Storage temperature	Tstg	–65 to +150	°C	

Recommended Operating Conditions

Item	Symbol	Ratings	Unit	Condition
Supply voltage	V _{cc}	2 to 6	V	
Input and output voltage	V _I , V _O	0 to V _{cc}	V	
Operating temperature	Та	-40 to +85	°C	
Input rise and fall time	tr, tf	8	ns/V	$V_{CC} = 3.0 V$
(except Schmitt inputs)				V _{cc} = 4.5 V
V_{IN} 30% to 70% V_{CC}				V _{cc} = 5.5 V



DC Characteristics

ltem	Sym- bol	Vcc (V)	1	Га = 25°	C	Ta = -40 to +85°C		Unit	Condition
			min.	typ.	max.	min.	max.		
Input Voltage	V _{IH}	3.0	2.1	1.5	—	2.1	—	V	$V_{OUT} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$
		4.5	3.15	2.25	_	3.15	_		
		5.5	3.85	2.75	_	3.85	_		
	V _{IL}	3.0	—	1.50	0.9	—	0.9		$V_{OUT} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$
		4.5	—	2.25	1.35	—	1.35		
		5.5	—	2.75	1.65	—	1.65		
Output voltage	V _{OH}	3.0	2.9	2.99	—	2.9	—	V	$V_{IN} = V_{IL} \text{ or } V_{IH}$
		4.5	4.4	4.49	—	4.4	—		I _{OUT} = -50 μA
		5.5	5.4	5.49	—	5.4	—		
		3.0	2.58	—	—	2.48	—		$V_{IN} = V_{IL} \text{ or } V_{IH}$ $I_{OH} = -12 \text{ mA}$
		4.5	3.94	—	—	3.80	—		I _{OH} = -24 mA
		5.5	4.94	—	—	4.80	—		I _{OH} = -24 mA
	V _{OL}	3.0	—	0.002	0.1	—	0.1		$V_{IN} = V_{IL} \text{ or } V_{IH}$
		4.5	—	0.001	0.1	—	0.1		Ι _{ουτ} = 50 μΑ
		5.5	—	0.001	0.1	—	0.1		
		3.0	—	—	0.32	—	0.37		$V_{IN} = V_{IL} \text{ or } V_{IH}$ $I_{OL} = 12 \text{ mA}$
		4.5	—	—	0.32	—	0.37		$I_{OL} = 24 \text{ mA}$
		5.5	—	—	0.32	—	0.37		I _{OL} = 24 mA
Input leakage current	I _{IN}	5.5	—	—	±0.1	—	±1.0	μA	$V_{IN} = V_{CC} \text{ or } GND$
Dynamic output	I _{OLD}	5.5	_	_		86	_	mA	V _{OLD} = 1.1 V
current*	I _{OHD}	5.5	_	_	_	-75	_	mA	$V_{OHD} = 3.85 \text{ V}$
Quiescent supply current	I _{cc}	5.5	—	—	8.0	—	80	μA	$V_{\rm IN} = V_{\rm CC}$ or ground

*Maximum test duration 2.0 ms, one output loaded at a time.

AC Characteristics

			Ta = +25°C C _L = 50 pF				°C to +85°C = 50 pF	
Item	Symbol	V _{cc} (V)* ¹	Min	Тур	Max	Min	Max	Unit
Maximum clock	f _{max}	3.3	90	125	—	75	—	MHz
frequency		5.0	140	175	—	125	—	
Propagation delay	t _{PLH}	3.3	1.0	7.0	12.5	1.0	14.0	ns
Clock to output		5.0	1.0	5.5	9.0	1.0	10.0	
Propagation delay	t _{PHL}	3.3	1.0	7.0	13.0	1.0	14.5	ns
Clock to output		5.0	1.0	5.0	10.0	1.0	11.0	
Propagation delay	t _{PHL}	3.3	1.0	7.0	13.0	1.0	14.0	ns
MR to output		5.0	1.0	5.0	10.0	1.0	10.5	1

Note: 1. Voltage Range 3.3 is $3.3 \vee \pm 0.3 \vee$

Voltage Range 5.0 is 5.0 V \pm 0.5 V

AC Operating Requirements

			Ta = +25°C C _L = 50 pF		Ta = -40°C to +85°C C _∟ = 50 pF	
Item	Symbol	V _{cc} (V)* ¹	Тур	Guarantee	d Minimum	Unit
Setup time, HIGH or LOW	t _{su}	3.3	3.5	5.5	6.0	ns
Data to CP		5.0	2.5	4.0	4.5]
Hold time, HIGH or LOW	t _h	3.3	-2.0	0.0	0.0	ns
Data to CP		5.0	-1.0	1.0	1.0	
Clock pulse width	t _w	3.3	3.5	5.5	6.0	ns
HIGH or LOW		5.0	2.5	4.0	4.5	
MR Pulse width	t _w	3.3	2.0	5.5	6.0	ns
HIGH or LOW		5.0	1.5	4.0	4.5	1
Recovery time	t _{rec}	3.3	1.5	3.5	4.5	ns
MR to CP		5.0	1.0	2.0	3.0	1

 Note:
 1.
 Voltage Range 3.3 is 3.3 V ± 0.3 V

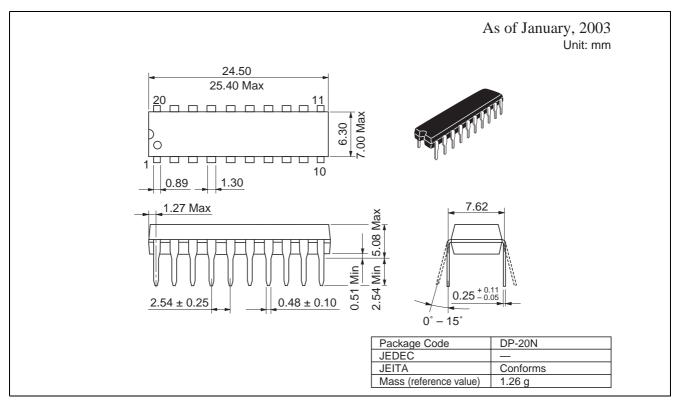
 Voltage Range 5.0 is 5.0 V ± 0.5 V

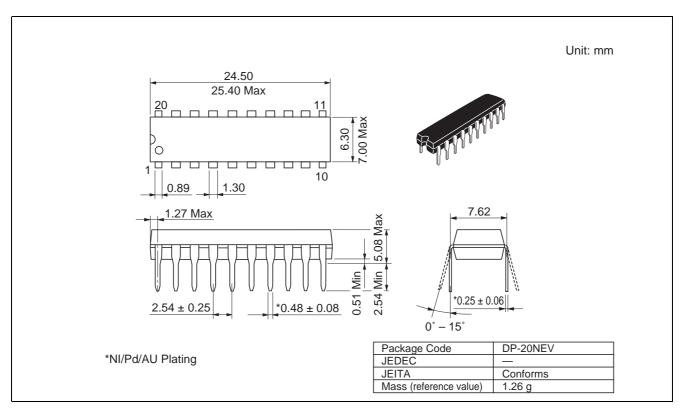
Capacitance

Item	Symbol	Тур	Unit	Condition
Input capacitance	C _{IN}	4.5	pF	$V_{\rm CC} = 5.5 \text{ V}$
Power dissipation capacitance	C _{PD}	50.0	pF	$V_{cc} = 5.0 V$

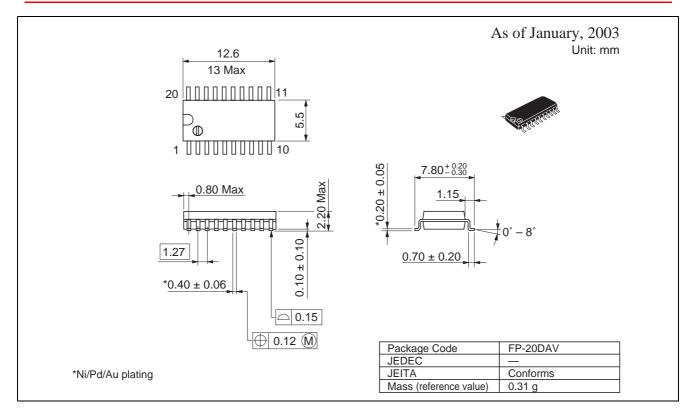


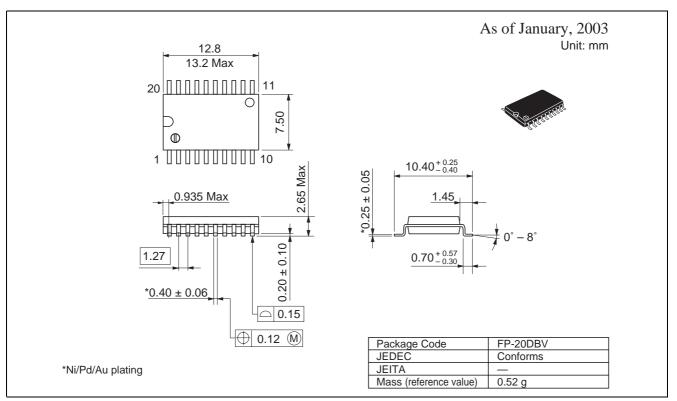
Package Dimensions











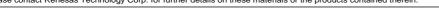


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